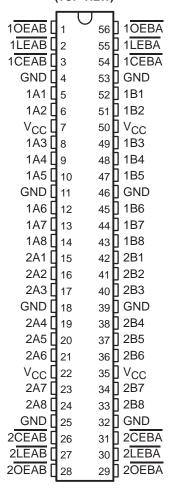
- **Members of the Texas Instruments** Widebus™ Family
- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$
- Distributed V_{CC} and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- Flow-Through Architecture Optimizes PCB
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OI})
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package **Using 25-mil Center-to-Center Spacings**

description

The 'ABT16543 16-bit registered transceivers contain two sets of D-type latches for temporary storage of data flowing in either direction. The 'ABT16543 can be used as two 8-bit transceivers or one 16-bit transceiver. Separate latch-enable (LEAB or LEBA) and output-enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable (CEAB) input must be low to enter data from A or to output data from B. If CEAB is low and \overline{LEAB} is low, the A-to-B latches are transparent; a subsequent low-to-high transition of LEAB puts the A latches in the storage mode. With CEAB and OEAB both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the CEBA, LEBA, and OEBA inputs.

SN54ABT16543 . . . WD PACKAGE SN74ABT16543...DGG OR DL PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down, $\overline{\sf OE}$ should be tied to ${\sf V}_{\sf CC}$ through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16543 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT16543 is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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SN54ABT16543, SN74ABT16543 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS087C - FEBRUARY 1991 - REVISED JANUARY 1997

FUNCTION TABLE† (each 8-bit section)

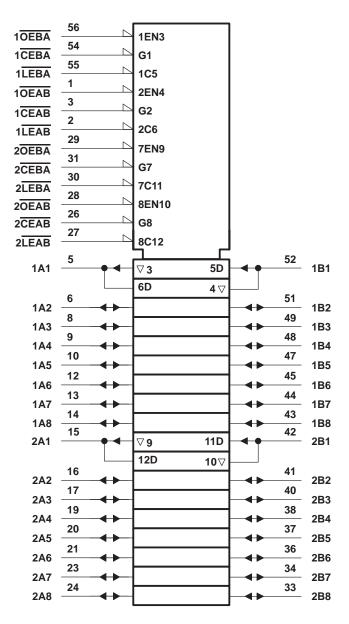
	INPUTS								
CEAB	LEAB	OEAB	Α	В					
Н	Х	Х	Х	Z					
Х	Χ	Н	Χ	Z					
L	Н	L	Χ	в ₀ ‡					
L	L	L	L	L					
L	L	L	Н	Н					

[†] A-to-B data flow is shown; B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.



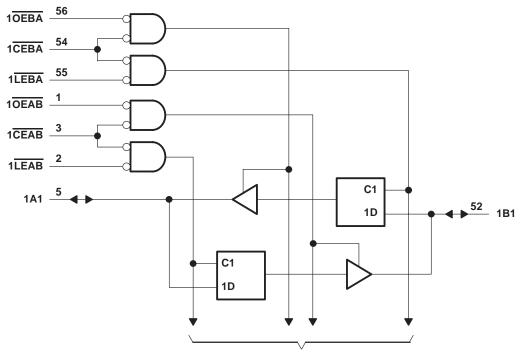
[‡] Output level before the indicated steady-state input conditions were established

logic symbol†

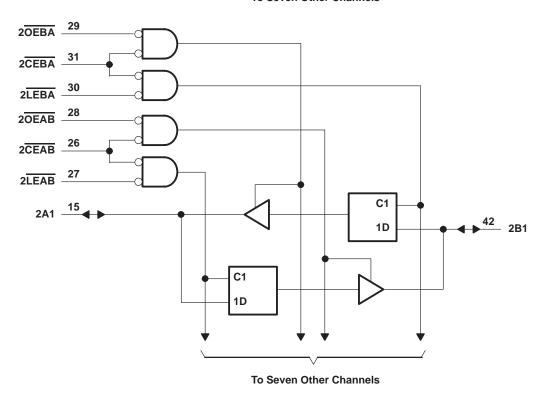


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To Seven Other Channels





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	$-0.5~\textrm{V}$ to 5.5 \textrm{V}
Current into any output in the low state, IO: SN54ABT16543	96 mA
SN74ABT16543	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	−50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T _{stq}	\dots -65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN54AB1	16543	SN74AB1	16543	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V	
VIL	Low-level input voltage		0.8		0.8	V	
VI	Input voltage		0	Vcc	0	VCC	V
loh	High-level output current			-24		-32	mA
loL	IOL Low-level output current					64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	T _A Operating free-air temperature				-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

SN54ABT16543, SN74ABT16543 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAE	DAMETED	TEST COL	UDITIONS	Т	A = 25°C	;	SN54AB	Γ16543	SN74AB1	Γ16543	UNIT	
PAR	RAMETER	TEST CO	NULLIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNII	
٧ıĸ		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
V		V _{CC} = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				V	
		VCC = 4.5 V	I _{OH} = -32 mA	2*					2			
V/		V 45V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		V _{CC} = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V	
V _{hys}					100						mV	
l _l	Control inputs	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		±1		±1	μΑ	
-	A or B ports	1				±100		±100		±100	-	
lozh‡		V _{CC} = 5.5 V,	V _O = 2.7 V			50**		10		50	μΑ	
lozL [‡]		$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			-50**		-10		-50	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ	
I _{CEX}		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ	
ΙΟ [§]		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-200	-50	-200	-50	-200	mA	
		V _{CC} = 5.5 V,	Outputs high			2		2		2		
ICC	A or B ports	$I_{O} = 0$,	Outputs low	35		35		35	mA			
		$V_I = V_{CC}$ or GND	Outputs disabled			2		2		2		
ΔICC¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				0.5		0.5		0.5	mA	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			3						pF	
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			8.5						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V _{CC} =	= 5 V, 25°C	SN54AB1	Г16543	SN74AB1	16543	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX		
t _W	Pulse duration, LEAB or LEBA low		4		4		4		ns	
	Cotors the adole haters IEAR as IERA	High	1.5		1.5		1.5		no	
t _{su}	Setup time, data before LEAB↑ or LEBA↑	Low	3.5		3.5		3.5		ns	
+.	Hold time and the office I EAR'S on I EDA'S	High	1.5		1.5		1.5		ne	
t _h	Hold time, data after LEAB↑ or LEBA↑	Low	2		2		2		ns	



^{**} These limits apply only to the SN74ABT16543.

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters IOZH and IOZL include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

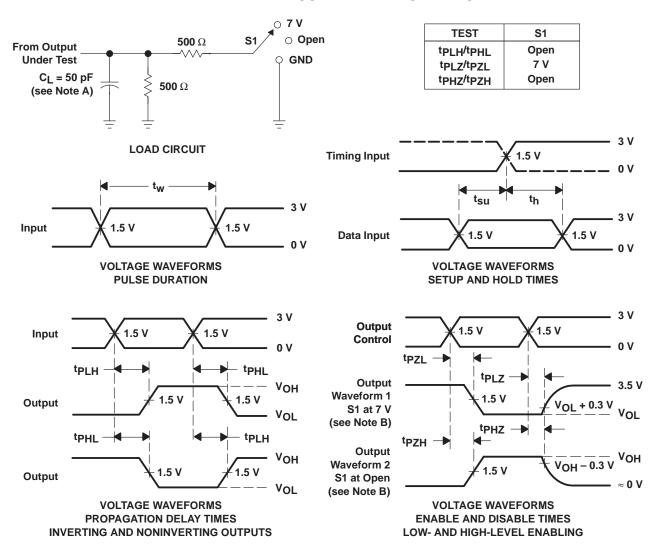
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

				SN5	4ABT16	543		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V A = 25°C	<i>'</i> ,	MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	A or B	B or A	0.8	2.5	3.3	0.8	3.9	ns
t _{PHL}	AOIB	BULK	0.9	2.7	4.4	0.9	5.2	115
tPLH	Œ	A or B	1	3.1	4.3	1	5.3	ns
^t PHL	LE	AOIB	1.2	3.3	4.8	1.2	5.7	113
^t PZH	ŌĒ	A or B	0.8	3.4	4.3	0.8	5.3	ns
tPZL	OE	AOID	1.1	3.8	7	1.1	7.9	
t _{PHZ}	ŌĒ	A or B	1.9	4	6.3	1.9	7.2	ne
t _{PLZ}	OE	AOID	1.6	3.3	4.6	1.6	5	ns
^t PZH	CE	A or B	0.9	3.8	4.9	0.9	6.3	no
t _{PZL}	CE	AUID	1.2	4.2	6.8	1.2	7.9	ns
^t PHZ	CE	A or B	2	4.5	6.4	2	7.3	nc
t _{PLZ}	CE	AUID	1.7	3.9	5.1	1.7	5.6	ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

				SN7	4ABT16	543			
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C	C = 5 V \ = 25°C	/, ;	MIN	MAX	UNIT	
			MIN	TYP	MAX				
t _{PLH}	A or B	B or A	1	2.5	3.3	1	3.8	ns	
^t PHL	AOID	BULK	1	2.7	4.4	1	5.1	113	
^t PLH	<u>.</u>	A or B	1	3.1	4.3	1	5.2	ns	
t _{PHL}	LE	AOID	1.2	3.3	4.8	1.2	5.6	115	
^t PZH	ŌĒ	A or B	1	3.4	4.3	1	5.2	ns	
t _{PZL}	OE .	AUID	1.1	3.8	5.9	1.1	7	115	
t _{PHZ}	ŌĒ	A or B	1.9	4	5	1.9	5.7		
t _{PLZ}	OE OE	AUID	1.6	3.3	4.2	1.6	4.6	ns	
^t PZH		A or B	1	3.8	4.9	1	6.2		
t _{PZL}	CE	AUID	1.2	4.2	6.5	1.2	7.8	ns	
^t PHZ	CE	A or B	2	4.5	5.6	2	6.6		
t _{PLZ}	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	AUID	1.7	3.9	5.1	1.7	5.4	ns	

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Q} = 50 Ω , t_{f} \leq 2.5 ns, t_{f} \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9324101MXA	ACTIVE	CFP	WD	56	1	TBD	A42 SNPB	N / A for Pkg Type
74ABT16543DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABT16543DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16543DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16543DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16543DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16543DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16543DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ABT16543WD	ACTIVE	CFP	WD	56	1	TBD	A42 SNPB	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16543DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74ABT16543DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16543DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74ABT16543DLR	SSOP	DL	56	1000	346.0	346.0	49.0

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

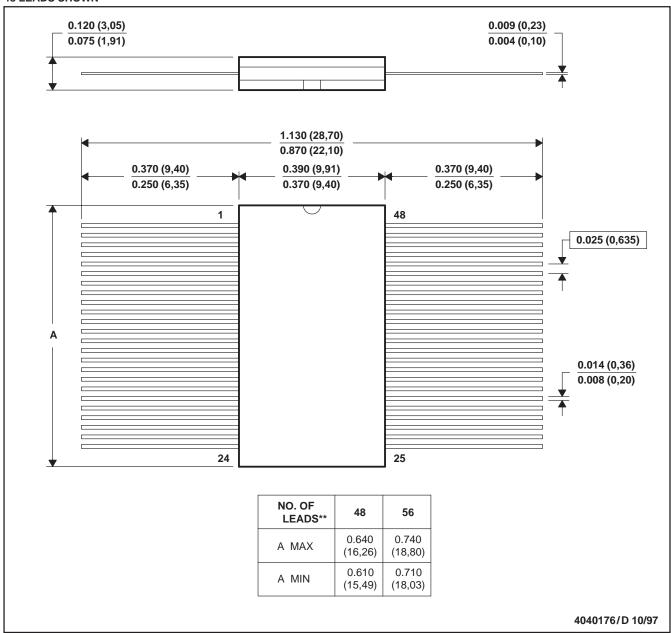
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB

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